

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Applica	nts: Christopher J. Kelly, et al.	§	Art Unit:	2827
Serial No.:	09/955,230	§ §		
Filed:	September 18, 2001	§ §	Examiner:	Tuan T. Dinh
	Printed Circuit Board Routing and Power Delivery for High	§ § §	Docket No.	ITL.0644US (P12307)

Commissioner for Patents Washington, D.C. 20231

## REPLY TO OFFICE ACTION DATED NOVEMBER 6, 2002

Dear Sir:

Please rewrite claims 11, 13. 14 and 20 as follows:

- TECHNOLOGY CENTER 2800 (Amended) The printed circuit board of claim 6, wherein the ground plane has an outer boundary that circumscribes a projection of the supply voltage plane onto the supply voltage plane layer.
- (Amended) The printed circuit board of claim 6, wherein the ground plane 13. reduces an inductance.
- 14. (Amended) The printed circuit board of claim 1, wherein the supply voltage reduces an inductance.

Date of Deposit: January 29, 2003

I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated above and is addressed to the for Patents, Washington, DC 20231.

Debra Cutrona

## 20. (Amended) A method comprising:

for each high frequency component to be mounted on a printed circuit board, embedding an associated supply voltage plane in a signal layer of the printed circuit board to provide power to the component, the signal layer being used to communicate high frequency signals associated with the high frequency component or components.